

GooLED

GooLED-LG-11080 Pin Fin Heat Sink Φ 110mm for LG Innotech

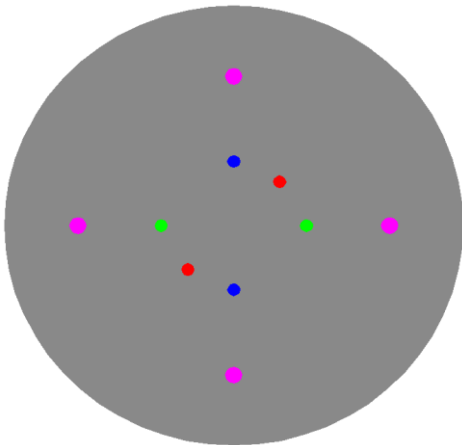
Features VS Benefits

- * The GooLED-LG-11080 LG Innotech Pin Fin LED Heat Sinks are specifically designed for luminaires using the LG Innotech LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 2,500 to 7,000 lumen.
- * Thermal resistance range R_{th} 1.14°C/W.
- * Modular design with mounting holes foreseen for direct mounting of LG Innotech COB series.
- * Diameter 110.0mm - standard height 80.0mm Other heights on request.
- * Forged from highly conductive aluminum.



Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of LG Innotech COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.



LG Innotech LED Modules directly Mounting Options

LG Innotech 42W&56W COB series.

- LEMWM28D80xxxxxx;
- LEMWM28D90xxxxxx;
- LEMWM28E80xxxxxx;
- LEMWM28E90xxxxxx;

With the Zhaga Book 3 holders for the green indicator marks.
 TE Connectivity Holder: 2213480-1;
 BJB Holder:47.319.2030.50;
 Without the holders for the blue indicator marks.
 Direct mounting with machine screws M3x6.5mm.

LG Innotech 21W&32W COB series.

- LEMWM24980xxxxxx;
- LEMWM24990xxxxxx;
- LEMWM24B80xxxxxx;
- LEMWM24B90xxxxxx;

With the Zhaga Book 3 holders for the green indicator marks.
 TE Connectivity Holder: 2213130-1;
 BJB Holder:47.319.2011.50;
 Without the holders for the red indicator marks.
 Direct mounting with machine screws M3x6.5mm.

With the LEDiL products:
 Olivia series: FN14637-S; FN14828-M;
 Stella Series: FN13xxx-xx; FN14xxx-xx; FN15xxx-xx;
 Stella Series mounting hole for the pink indicator marks.
 Direct mounting with machine screws M4x8.5mm.

Mounting Options and Drawings & Dimensions

Example:GooLED-LG-11080-B-1,2

Example:GooLED-LG-110 **1** - **2** - **3**

1 Height (mm)

2 Anodising Color

B-Black

C-Clear

Z-Custom

3 Mounting Options - see graphics for details Combinations available

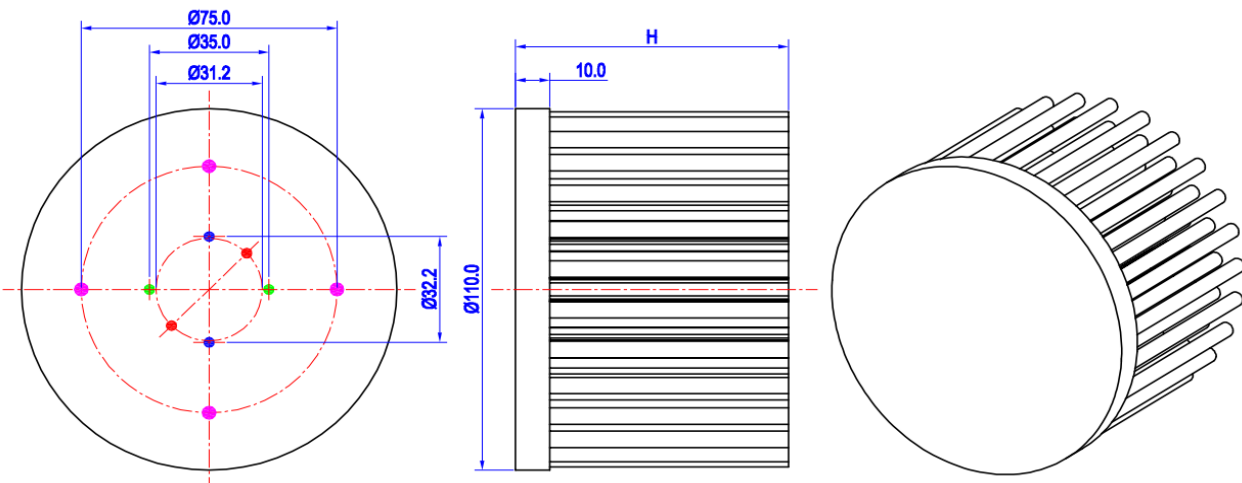
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means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	LEDiL products		THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
			Stella Series	Olivia series			
1	21W&32W COB	/	FN13xxx-xx; FN14xxx-xx; FN15xxx-xx;	FN14637-S; FN14828-M;	M3	6.5mm	31.2mm/ 2-@180°
2	42W&56W COB	/			M3	6.5mm	32.2mm/ 2-@180°
3	21W&32W COB	BJB Holder 47.319.2011.50 TE Holder 2213130-1			M3	6.5mm	35.0mm/ 2-@180° (Zhaga Book 3)
	42W&56W COB	BJB Holder 47.319.2030.50 TE Holder 2213480-1					
4	LEDiL Lens	/	Stella Series	/	M4	8.5mm	75.0mm/ 4-@90°



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GooLED-LG-11080 Pin Fin Heat Sink $\Phi 110\text{mm}$ for LG Innotek

The product data table

	Model No.	GooLED-LG-11080
	Heatsink Size	$\Phi 110 \times H 80\text{mm}$
	Heatsink Material	AL1070
	Finish	Black Anodized
	Weight (g)	617.0
	Dissipated power ($T_{hs-amb, 50^\circ\text{C}}$)	44.0 (W)
	Cooling surface area (mm^2)	129119
	Thermal Resistance (R_{hs-amb})	1.14 ($^\circ\text{C/W}$)

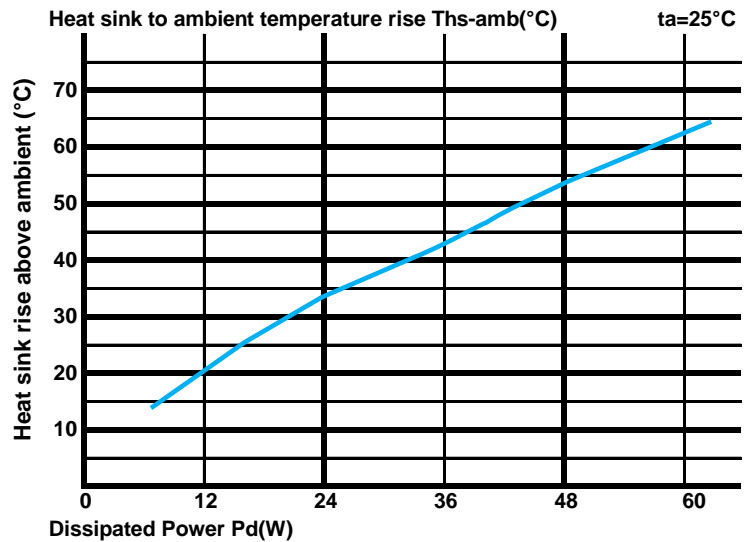
The thermal data table

* Please be aware the dissipated power P_d is not the same as the electrical power P_e of a LED module.

* To calculate the dissipated power please use the following formula: $P_d = P_e \times (1 - \eta_L)$.

P_d - Dissipated power ; P_e - Electrical power ; η_L = Light efficiency of the LED module;

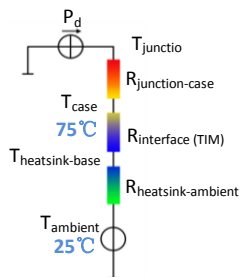
Dissipated Power P_d (W)	$P_d = P_e \times (1 - \eta_L)$	Heat sink to ambient thermal resistance R_{hs-amb} ($^\circ\text{C/W}$)	Heat sink to ambient temperature rise T_{hs-amb} ($^\circ\text{C}$)
		GooLED-LG-11080	
12.0		1.67	20.0
24.0		1.38	33.0
36.0		1.17	42.0
48.0		1.10	53.0
60.0		1.03	62.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (T_{hs} - T_a) / P_d$

θ - Thermal Resistance [$^\circ\text{C/W}$]; T_{hs} - Heatsink temperature ; T_a - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface (TIM)}$ [$^\circ\text{C/W}$], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [$^\circ\text{C/W}$], and the ambient temperature is $T_{ambient}$ [$^\circ\text{C}$].

*Thermal resistances outside the package $R_{interface (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used:

$$T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot P_d + T_{ambient}$$